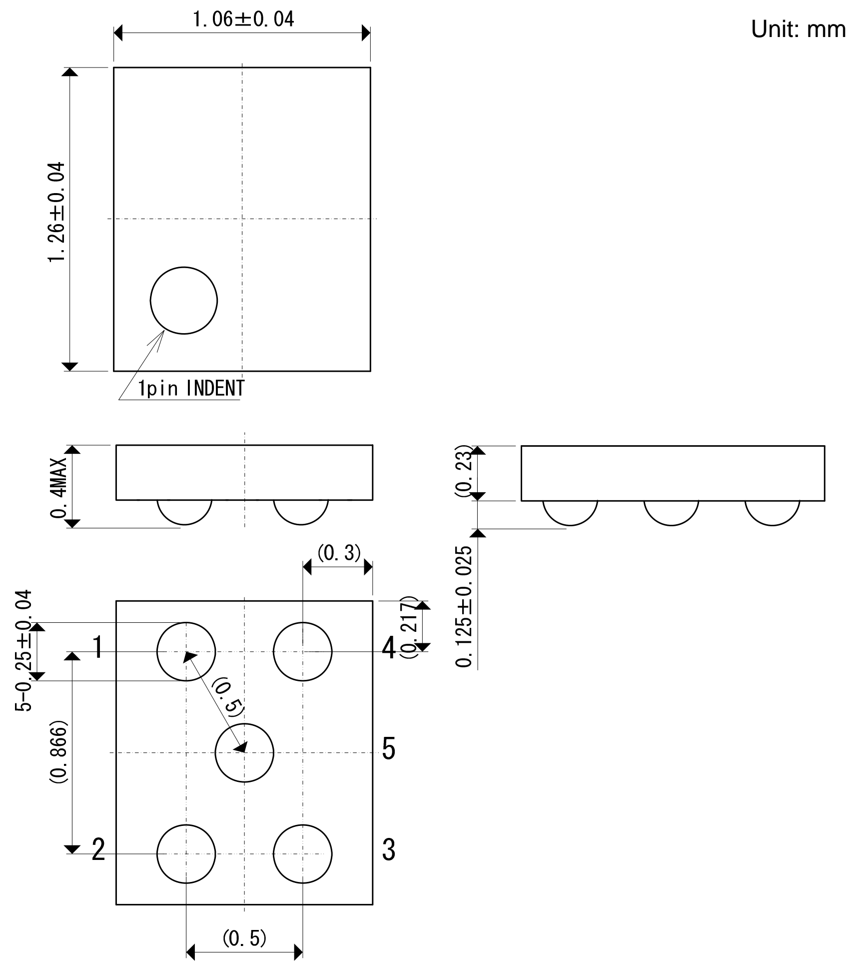
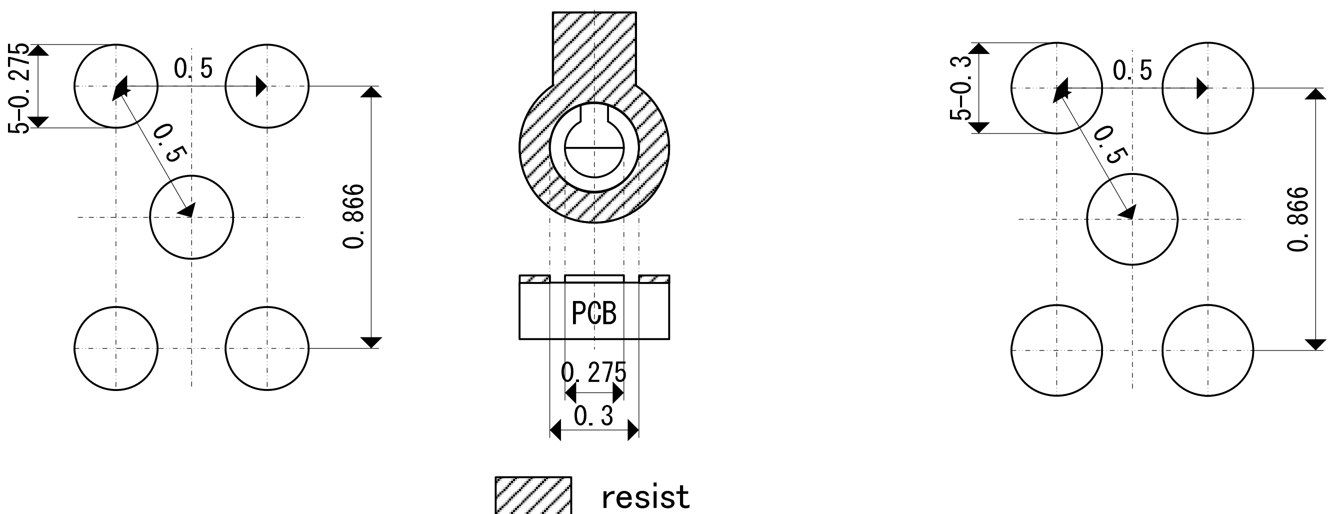
Packaging Information / Reference Pattern Layout Dimensions

●WLP-5-03

Unit: mm



●Reference Pattern Layout ●Reference Pattern Layout Detail ●Reference Metal Mask Design

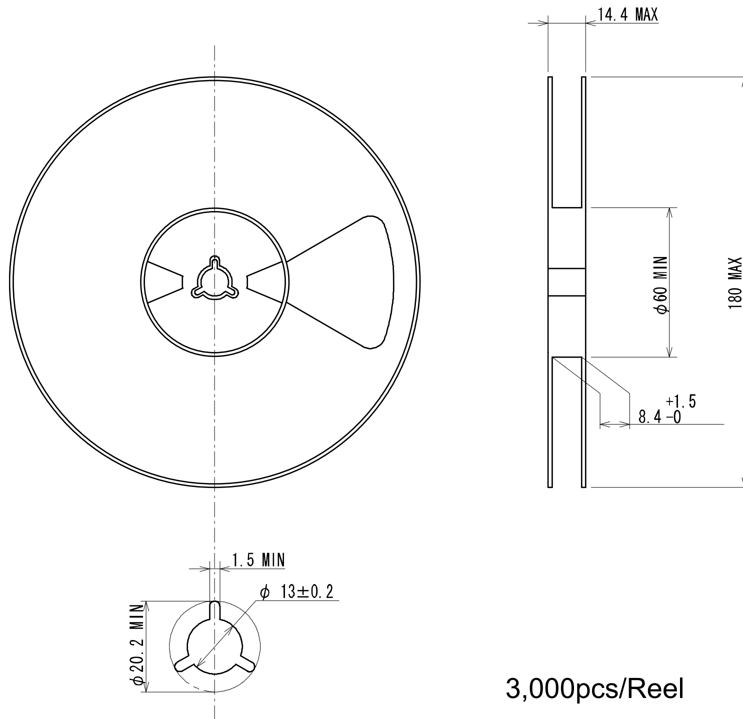


テーピング仕様/ Taping Specifications

WLP-5-03

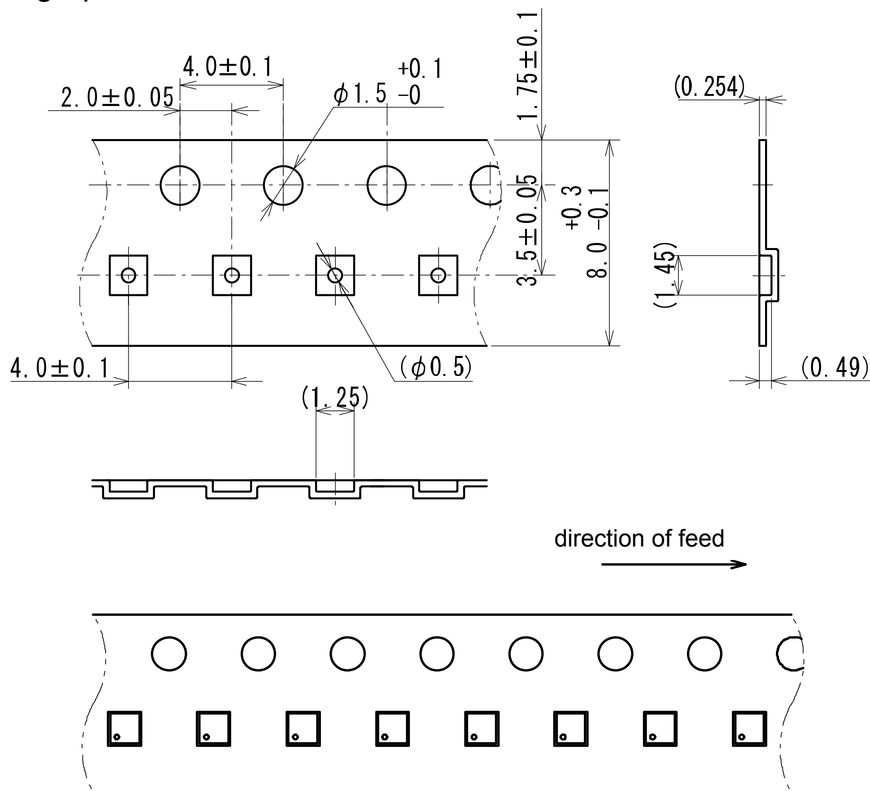
●リール/Reel

Unit: mm



3,000pcs/Reel

●テーピング仕様/Taping Specifications



R Type :[Device orientation : Right]

Standard feed

●WLP-5-03 Power Dissipation

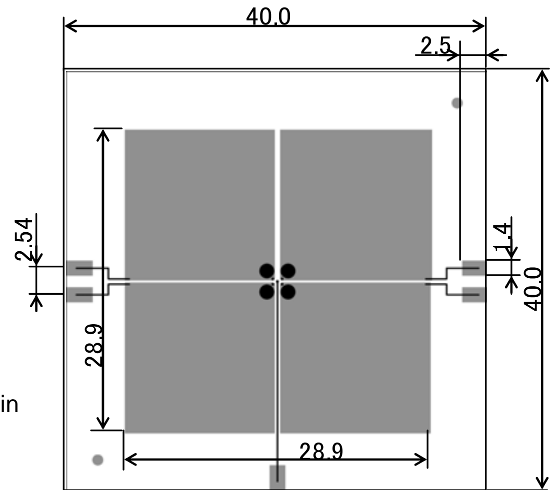
Power dissipation data for the WLP-5-03 is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Conditions

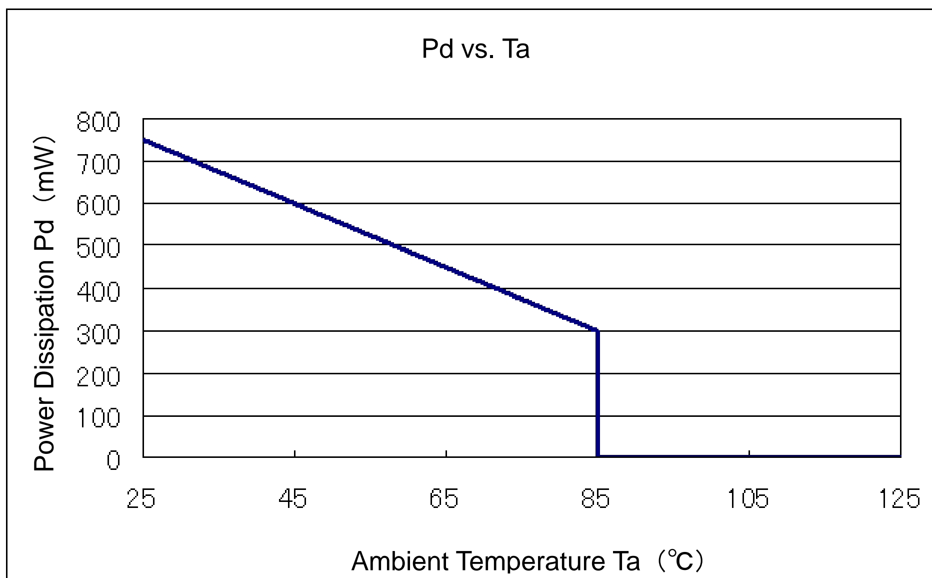
Condition	: Mount on a board
Ambient	: Natural convection
Soldering	: Lead (Pb) free
Board Dimensions	: 40mm×40mm（1600mm^2 in one side）
Metal Area	: 1st Metal Layer about 50%
	2nd Inner Metal Layer about 50%
	3rd Inner Metal Layer about 50%
	4th Metal Layer about 50%
	4 separations is each layer connected to each pin
Material	: Glass Epoxy（FR-4）
Thickness	: 1.6mm
Through-hole	: 4 x 0.8 Diameter



2. Power Dissipation vs. Ambient temperature

Board Mount (Tjmax=125℃)

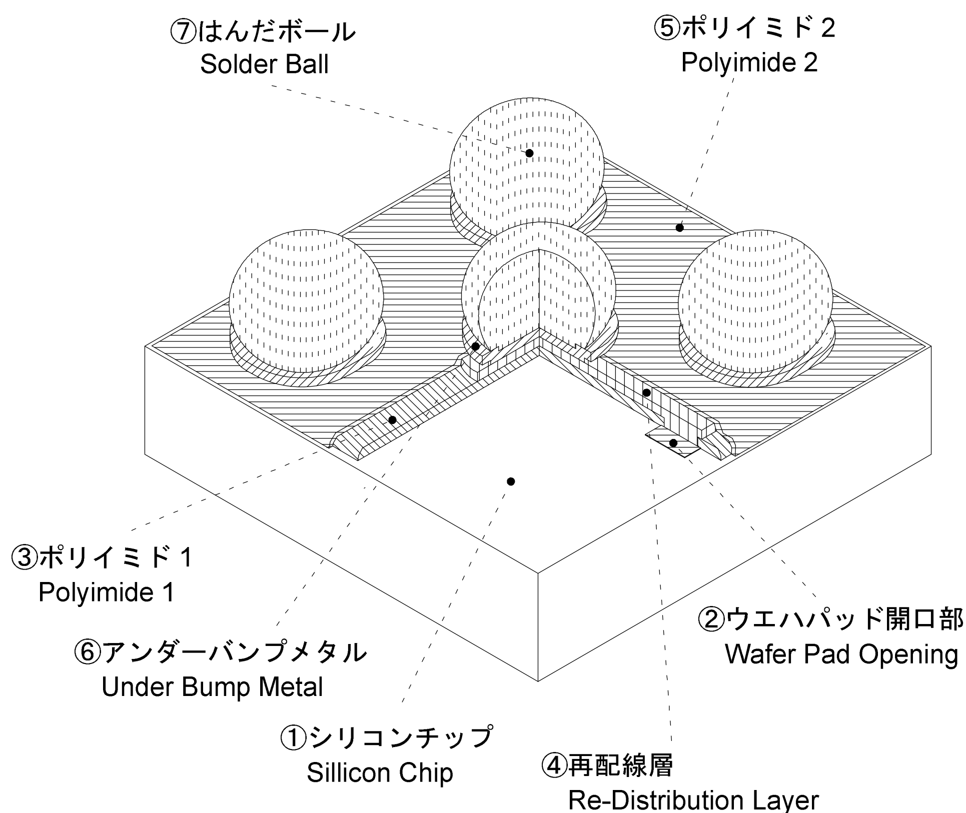
Ambient Temperature (℃)	Power Dissipation Pd (mW)	Thermal Resistance (℃/W)
25	750	133.33
85	300	



TOIREX

WLP-5-03構造図
WLP-5-03 Perspective

RoHS対応品
RoHS Compliance



項 目 Item		材 料 Material	備 考 Note
①	シリコンチップ Sillicon Chip	シリコン Sillicon	
②	ウエハパッド開口部 Wafer Pad Opening	アルミニウム Alminium	
③	ポリイミド 1 Polyimide 1	ポリイミド Polyimide	
④	再配線層 Re-Distribution Layer	銅 + チタン Copper + Titanium	
⑤	ポリイミド 2 Polyimide 2	ポリイミド Polyimide	
⑥	アンダーバンプメタル Under Bump Metal	銅 + チタン Copper + Titanium	
⑦	はんだボール Solder Ball	スズ + 銀 + 銅 Tin + Silver + Copper	

捺印表示 Marking	レーザー Laser marking